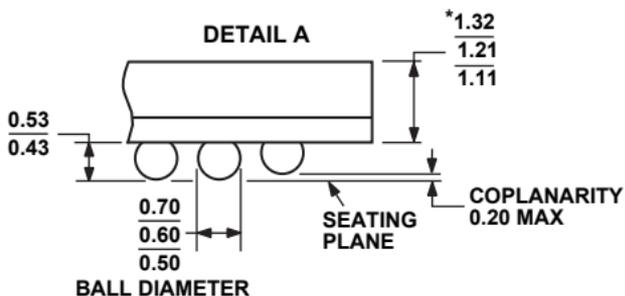
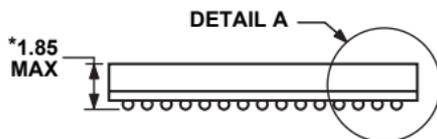
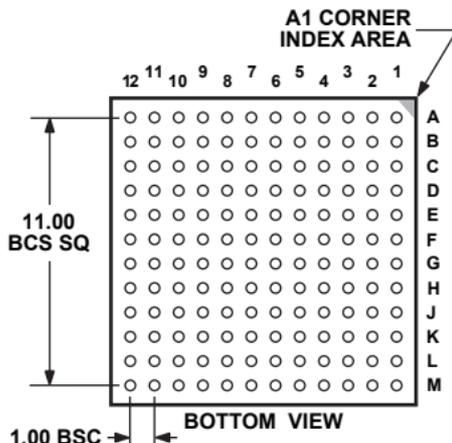
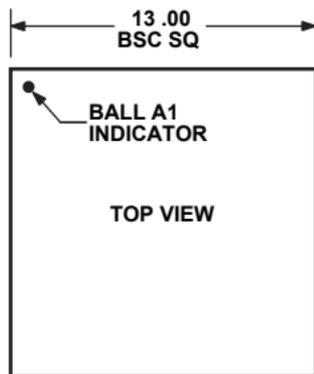


**144-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-144-3)**

Dimensions shown in millimeters



*COMPLIANT WITH JEDEC STANDARDS MO-192-AAD-1 WITH
EXCEPTION TO PACKAGE HEIGHT AND THICKNESS.